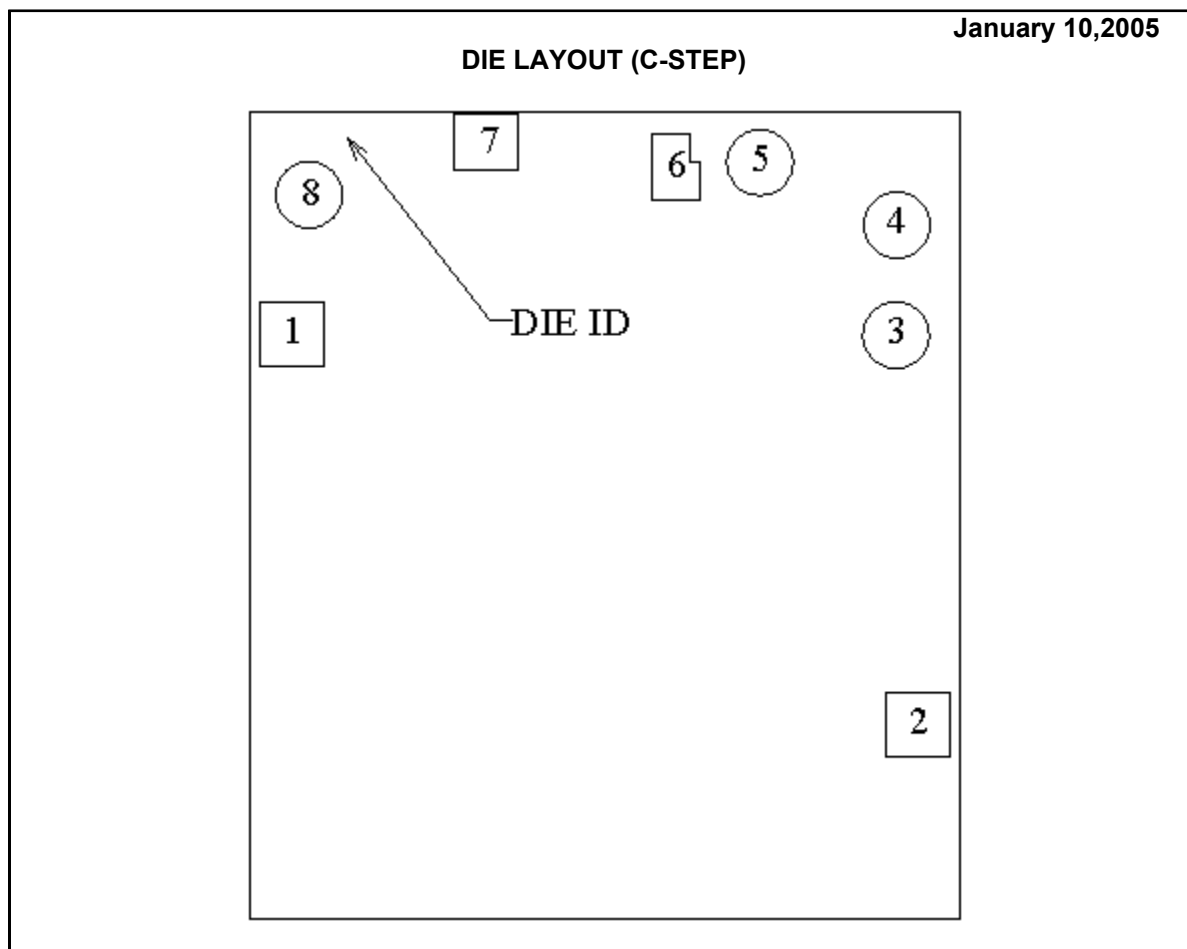


LM385-1.2 MDC MWC
MICROPOWER VOLTAGE REFERENCE DIODE



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	G185C	Bond Pad Opening Size (min)	117 μ m x 117 μ m
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1295 μ m x 1473 μ m 51.0mils x 58.0mils	Back Side Connection	Floating or Pad# 2
Thickness	330 μ m Nominal		
Min Pitch	1211 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
+	1	-572	330	117	x	117
-	2	572	-381	117	x	117
NC	3	533	330	117	x	117
NC	4	533	533	117	x	117
NC	5	284	643	117	x	117
NC	6	130	635	86	x	117
NC	7	-216	705	117	x	104
NC	8	-538	584	117	x	117

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